



## **SMT power inductors**

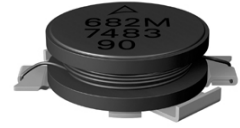
Size 10.4 × 10.4 × 3.0 (mm)

**Series/Type:**            **B82464A2**

**Date:**                    **March 2008**

Rated inductance 1  $\mu$ H to 330  $\mu$ H

Rated current 0.43 A to 6.8 A



### Construction

- Ferrite core
- Winding: enamel copper wire
- Winding welded to terminals

### Features

- Temperature range up to 150 °C
- High rated current
- Low DC resistance
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020C
- Qualified to AEC-Q200
- RoHS-compatible

### Applications

- Filtering of supply voltages
- Coupling, decoupling
- DC/DC converters
- Automotive electronics
- Industrial electronics

### Terminals

- Base material CuFe<sub>2</sub>P
- Layer composition Ag, Sn (lead-free)
- Electro-plated

### Marking

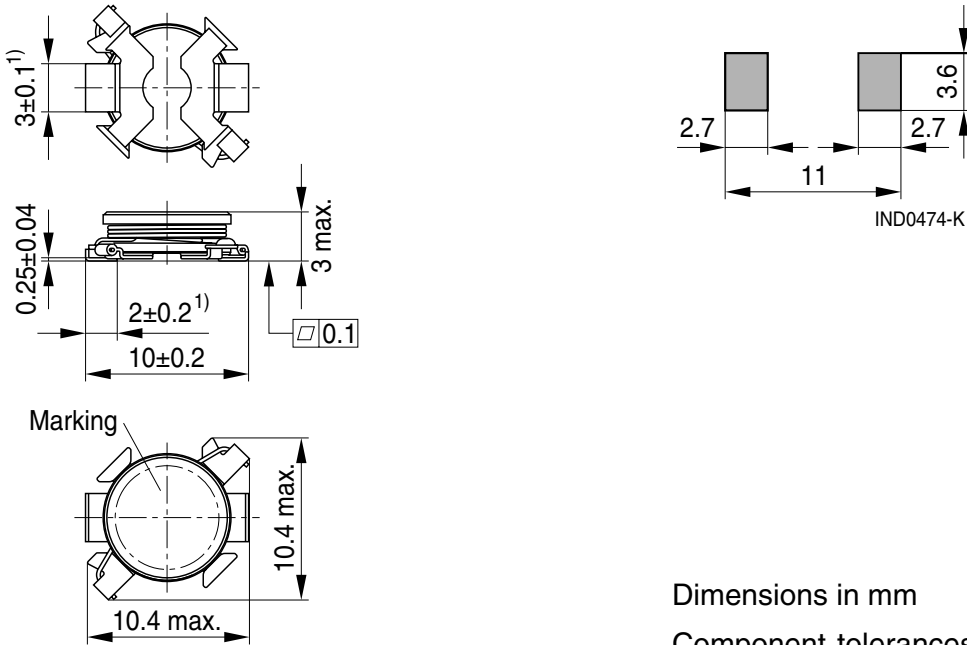
- Marking on component:  
Manufacturer, L value (nH, coded),  
L tolerance (coded), manufacturing date (YWWD),  
two last digits of work order
- Minimum data on reel:  
Manufacturer, ordering code, L value,  
quantity, date of packing

### Delivery mode and packing unit

- 16-mm blister tape, wound on 330-mm  $\varnothing$  reel
- Packing unit: 1250 pcs./reel

SMD

Dimensional drawing and layout recommendation



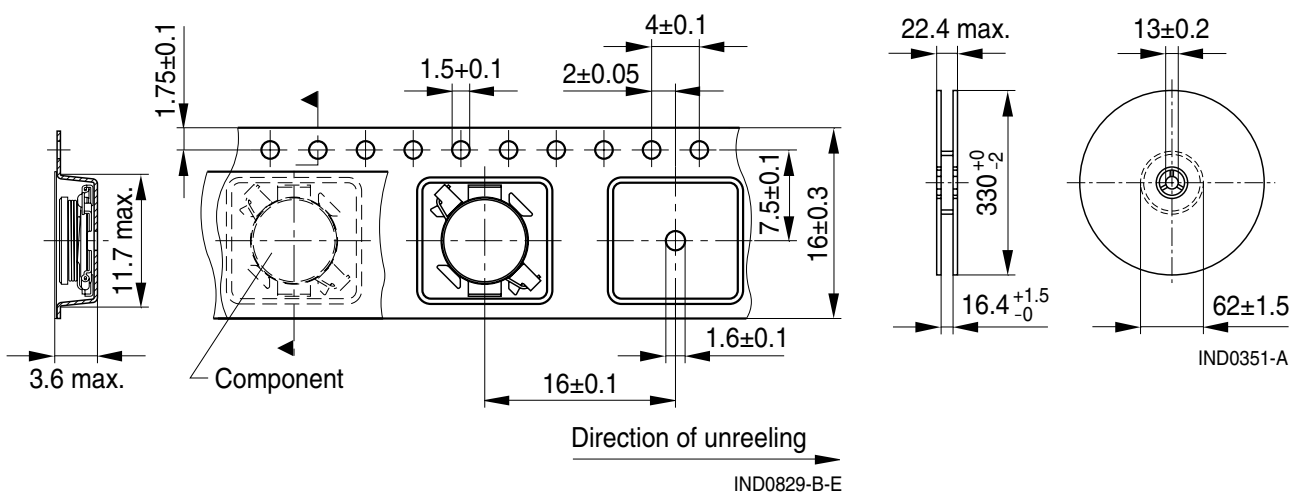
1) Soldering area

IND0473-E-E

Taping and packing

Blister tape

Reel



Dimensions in mm

**Technical data and measuring conditions**

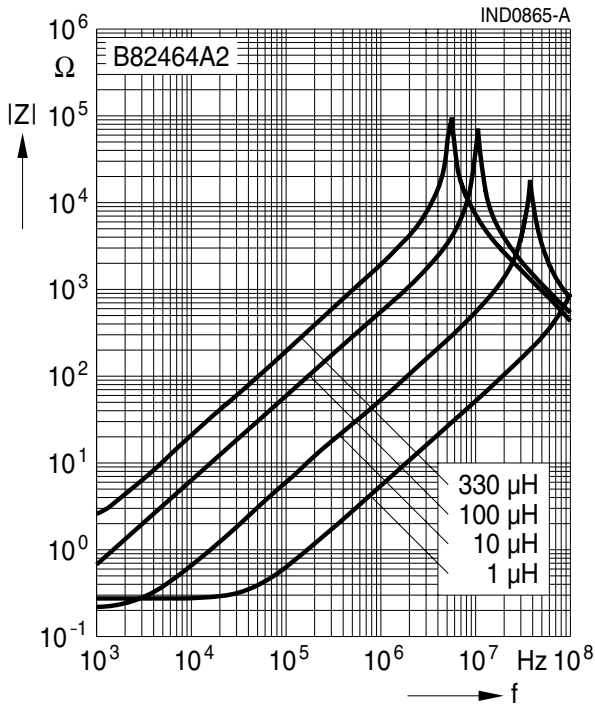
Rated inductance $L_R$	Measured with impedance analyzer Agilent 4294A at frequency $f_L$ , 0.1 V, 20 °C
Rated temperature $T_R$	85 °C
Rated current $I_R$	Max. permissible DC with temperature increase of $\leq 40$ K at rated temperature
Saturation current $I_{sat}$	Max. permissible DC with inductance decrease $\Delta L/L_0$ of approx. 10%
DC resistance $R_{max}$	Measured at 20 °C
Solderability (lead-free)	Dip and look method Sn95.5Ag3.8Cu0.7: (245 $\pm$ 5) °C, (5 $\pm$ 0.3) s Wetting of soldering area $\geq 90\%$ (based on IEC 60068-2-58)
Resistance to soldering heat	260 °C, 40 s (as referenced in JEDEC J-STD 020C)
Climatic category	55/150/56 (to IEC 60068-1)
Storage conditions	Mounted: -55 °C ... +150 °C Packaged: -25 °C ... +40 °C, $\leq 75\%$ RH
Weight	Approx. 1.5 g

**Characteristics and ordering codes**

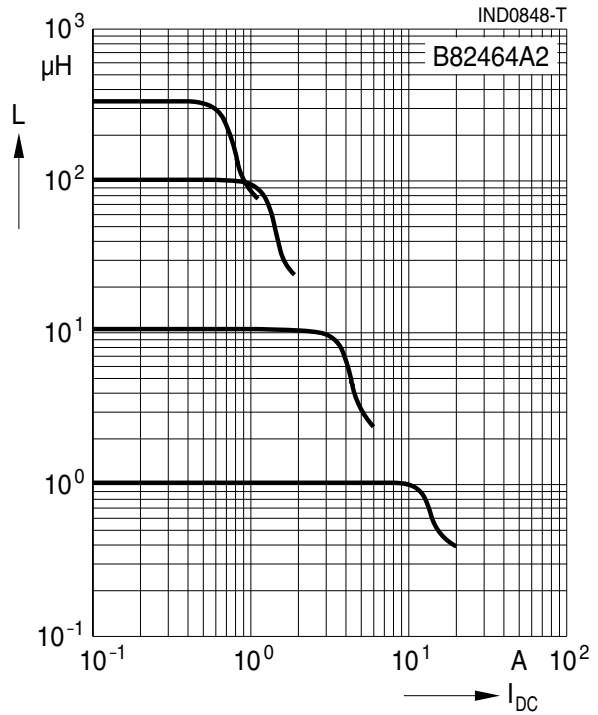
$L_R$ $\mu\text{H}$	Tolerance	$f_L$ MHz	$I_R$ A	$I_{sat}$ A	$R_{max}$ $\Omega$	Ordering code	
1.0	$\pm 20\% \triangleq M$	0.1	6.80	9.50	0.010	B82464A2102M000	
1.5		0.1	6.40	7.90	0.011	B82464A2152M000	
2.2		0.1	5.60	6.70	0.014	B82464A2222M000	
3.6		0.1	5.20	5.30	0.025	B82464A2362M000	
4.7		0.1	4.20	4.50	0.030	B82464A2472M000	
6.8		0.1	3.05	3.60	0.045	B82464A2682M000	
10		0.1	2.65	3.10	0.060	B82464A2103M000	
15		$\pm 10\% \triangleq K$	0.1	2.05	2.55	0.098	B82464A2153K000
22			0.1	1.72	2.05	0.135	B82464A2223K000
33			0.1	1.45	1.70	0.195	B82464A2333K000
47	0.1		1.26	1.45	0.260	B82464A2473K000	
68	0.1		1.18	1.20	0.360	B82464A2683K000	
100	0.1		0.86	0.95	0.550	B82464A2104K000	
150	0.1		0.67	0.82	0.830	B82464A2154K000	
220	0.1		0.56	0.69	1.15	B82464A2224K000	
330	0.1		0.43	0.57	1.72	B82464A2334K000	

SMD

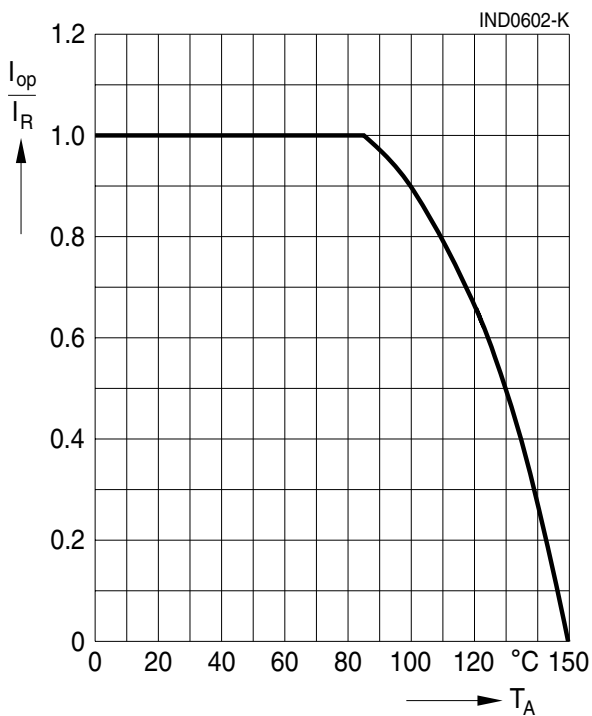
**Impedance |Z| versus frequency f**  
measured with impedance analyzer  
Agilent 4294A, typical values at 20 °C



**Inductance L versus DC load current I<sub>DC</sub>**  
measured with LCR meter Agilent 4275A,  
typical values at 20 °C



**Current derating I<sub>op</sub>/I<sub>R</sub>**  
**versus ambient temperature T<sub>A</sub>**  
(rated temperature T<sub>R</sub> = 85 °C)



## Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

## Important notes

The following applies to all products named in this publication:

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As a rule, EPCOS is either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an EPCOS product with the properties described in the product specification is suitable for use in a particular customer application.

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